

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT														
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT														
<b>CONVEYING PARTY DATA</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jae-Hyuk CHANG</td> <td>01/18/2011</td> </tr> <tr> <td>Seung-Jun LEE</td> <td>01/18/2011</td> </tr> <tr> <td>Hyun-Seok KIM</td> <td>01/18/2011</td> </tr> <tr> <td>Sung Hee LEE</td> <td>01/18/2011</td> </tr> <tr> <td>Gug-Rae JO</td> <td>01/18/2011</td> </tr> <tr> <td>Sin KWON</td> <td>01/18/2011</td> </tr> </tbody> </table>		Name	Execution Date	Jae-Hyuk CHANG	01/18/2011	Seung-Jun LEE	01/18/2011	Hyun-Seok KIM	01/18/2011	Sung Hee LEE	01/18/2011	Gug-Rae JO	01/18/2011	Sin KWON	01/18/2011
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<b>RECEIVING PARTY DATA</b>															
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<b>CORRESPONDENCE DATA</b>															
<p>Fax Number: (703)288-5139  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-288-5105        Email: patent@park-law.com</p> <p>Correspondent Name: H.C. Park &amp; Associates, PLC        Address Line 1: 8500 Leesburg Pike        Address Line 2: Suite 7500        Address Line 4: Vienna, VIRGINIA 22182</p>															
<b>ATTORNEY DOCKET NUMBER:</b>	P4068US00														

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**PATENT**  
**REEL: 025899 FRAME: 0633**

NAME OF SUBMITTER:

Hae-Chan Park

Total Attachments: 3

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### **ASSIGNMENT**

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☒ an application for United States Letters Patent entitled **METHOD FOR FORMING PATTERN AND METHOD FOR MANUFACTURING LIQUID CRYSTAL DISPLAY DEVICE** ("Application");

☐ upon which United States Letters Patent, Patent Number \_\_\_\_\_, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

**Samsung Electronics Co., Ltd.**  
416 Maetan-dong, Yeongtong-gu  
Gyeonggi-do  
Suwon-si  
Republic of Korea

**Samsung Electronics Co., Ltd.** herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries



and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Jae-Hyuk CHANG

Address: 306-702, Hansolmaeul Hanil Apt.  
Jeongja-dong, Bundang-gu, Gyeonggi-do  
Seongnam-si  
Republic of Korea

First Inventor's Signature:

*Chang, Jaehyuk*

Date:

*2011. 1. 18*

Second Inventor's Name: Seung-Jun LEE

Address: 502-1701, Sinjeong Maeul Seongji Apt.  
Pungdeokcheon 2-dong, Suji-gu, Gyeonggi-do  
Yongin-si  
Republic of Korea

Second Inventor's Signature:

*Seung Jun Lee*

Date:

*2011. 1. 18*

Third Inventor's Name: Hyun-Seok KIM

Address: 303-207, Mokryeon Woosung Apt.  
Beomgye-dong, Dongan-gu, Gyeonggi-do  
Anyang-si  
Republic of Korea

Third Inventors' Signature:

*Hyun-Seok Kim*

Date:

*2011. 1. 18*



Fourth Inventor's Name:

Sung Hee LEE

Address:

5 FL., CheongOh Bldg., 596  
Sinsa-dong, Gangnam-gu  
Seoul  
Republic of Korea

Fourth Inventor's Signature:

Date:

2011.1.18

Fifth Inventor's Name

Gug-Rae JO

Address:

201-205 Tra Palace, Myeongam-ri, Tangeong-myeon  
Chungcheongnam-do  
Asan-si  
Republic of Korea

Fifth Inventor's Signature:

Date:

2011.1.18

Sixth Inventor's Name:

Sin KWON

Address:

935-403, Byeokjeokgol 9-danji Apt.  
Yeongtong 2-dong, Yeongtong-gu, Gyeonggi-do  
Suwon-si  
Republic of Korea

Sixth Inventor's Signature:

Date:

2011.1.18